Overview



Front

- 1. Pull-up webcam and microphone
- 2. Speakers

3. SD media card reader

Overview

HP 200 G4 22 All-in-One PC



Rear

- 1. Optical disc drive (optional)
- 2. Power button
- 3. Pull-up webcam
- 4. Microphone/Headphone Combo Jack
- 5. RJ-45 (network) jack

- 6. HDMI 1.4 out connector
- 7. Power connector
- 8. Two (2) Type-A Hi-Speed USB 480Mbps signaling rate ports
- 9. Two (2) Type-A SuperSpeed USB 5Gbps signaling rate port
- 10. Standard cable lock slot

AT A GLANCE

- Choice of Windows 10 Pro, Windows 10 Home, and FreeDOS
- Integrated All-in-One form factor
- 21.5-inch diagonal widescreen Full HD anti-glare display
- Intel® 10th generation processors, featuring integrated Intel® UHD Graphics
- Up to 32GB of DDR4 Synchronous Dynamic Random-Access Memory (SDRAM)
- Integrated 10/100/1000 Gigabit LAN Ethernet Controller
- Optional Wi-Fi 5 (802.11ac) wireless connectivity
- Integrated HD audio card and stereo speakers
- Integrated 5MP pull-up camera to ensure no accidental recording to safeguard user's privacy
- Expandable storage options with up to 512GB SSD and 2TB HDD
- Optional HP Slim Tray DVD Writer 8X Optical Drive
- 3-in-1 Media Card Reader
- TPM 2.0 support
- Low halogen¹ materials,
- Protected by HP Services. Terms and conditions vary by country. Certain restrictions and exclusions apply.

1. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

NOTE: See important legal disclosures for all listed specs in their respective features sections.





OPERATING SYSTEMS

Preinstalled Windows 10 Pro 64¹

Windows 10 Home 641

Windows 10 Pro 64 (National Academic License)1,2

Pre-installed (other) FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

PROCESSORS*

Intel® 10th Generation Core™ Processors

Intel® Core™ i5-10210U Processor
1.6 GHz base frequency
Up to 4.2 GHz max. turbo frequency with Intel® Turbo Boost**
6 MB cache, 4 cores, 8 threads
Intel® UHD Graphics
Supports DDR4 memory up to 2666 MT/s data rate

Intel® Core™ i3-10110U Processor
2.1 GHz base frequency
Up to 4.1 GHz max. turbo frequency with Intel® Turbo Boost**
4 MB cache, 2 cores, 4 threads
Intel® UHD Graphics
Supports DDR4 memory up to 2666 MT/s data rate

Intel® Pentium® Processors

Intel® Pentium® Silver J5040 Processor
2.0 GHz base frequency
Up to 3.2 GHz max. turbo frequency with Intel® Turbo Boost**
4 MB cache, 4 cores, 4 threads
Intel® UHD Graphics 605
Supports DDR4 memory up to 2400 MT/s data rate

*Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

**Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

NOTE: In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.



Features

GRAPHICS

Integrated

Intel® UHD Graphics Intel® UHD Graphics 605

NOTE: Intel® integrated UHD Graphics varies by processor

DISPLAY

Non-Touch

21.5" diagonal FHD IPS anti-glare WLED-backlit (1920 x 1080) 21.5" diagonal FHD VA anti-glare WLED-backlit (1920 x 1080)

STORAGE AND DRIVES¹

M.2 PCIe NMVe Solid State Drives (SSD)

256GB 2280 PCIe NVMe Solid State Drive 512GB 2280 PCIe NVMe Solid State Drive 128GB 2280 PCIe NVMe TLC Solid State Drive 256GB 2280 PCIe NVMe TLC Solid State Drive 512GB 2280 PCIe NVMe TLC Solid State Drive

3.5 inch 7200RPM SATA Hard Disk Drives (HDD)

500GB 7200RPM 3.5in HDD 1TB 7200RPM 3.5in HDD 2TB 7200RPM 3.5in HDD

Optical Disc Drives

9.5mm Ultra Slim DVD-Writer

Media Card Reader

SD Card Reader with 3-in1 Interface (Supports SD, SDHC, SDXC)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) is reserved for system recovery software.

MEMORY

Maximum

DDR4 SODIMM up to 2666MT/s

Memory Slots

2 SODIMM

Available Configurations

4GB (4GB x1)

8GB (4GB x2)

8GB (8GB x1)

16GB (8GB x2)

16GB (16GB x1)

32GB (16GB x2)

NOTE: Actual data rate is determined by both the system's configured processor and memory module installed.





NETWORKING/COMMUNICATIONS

Wireless LAN*

Realtek® RTL8822CE Wi-Fi 51 (802.11ac) 2x2 Wi-Fi M.2 Card² Realtek® RTL8821CE Wi-Fi 51 (802.11ac) 1x1 Wi-Fi M.2 Card²

Ethernet (RJ-45) Integrated

Realtek® RTL8111HSH-CG Gigabit Ethernet Controller

*Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 is backwards compatible with prior 802.11 specs.

- 1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.
- 2. Must be configured at time of purchase.

AUDIO/MULTIMEDIA

High Definition Audio

Integrated Realtek ALC3247 Audio Codec High performance integrated stereo speakers 3.5mm combo (microphone/headphone) jack

Webcams & Mic

Integrated 5MP webcam, Up to 30 frames/sec, dual array microphone included

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboards

HP Universal USB Wired Keyboard

Mice

HP USB Optical Mouse HP USB Hardened Optical Mouse HP USB Universal Mouse

NOTE: Availability may vary by country





SOFTWARE AND SECURITY

HP Support

HP PC Hardware Diagnostics HP Cloud Recovery HP Support Assistant

Internet Security and Antivirus

McAfee LiveSafe (30-day subscription)1

Product Setup

HP JumpStarts

Security Features

Trusted Platform Module (TPM) 2.0 (firmware)^{2,3}

Productivity

Xerox® DocuShare® (90 days free trial offer)4

- 1. 30 day trial period. Internet access required to receive updates. First update included. Subscription required for updates thereafter
- 2. TPM feature will not be supported on machines pre-configured with FreeDOS and Linux
- 3. In selected countries, machines pre-configured with Windows OS will be shipped with TPM disabled.
- 4. Simply sign up and start using Xerox® DocuShare® Go. No credit card. No obligation. Data will become unavailable unless a subscription is entered before the end of the 90 day free trial period. See visit https://xerox.com/docusharego for details.

POWER

Power Supply

HP Smart 65W External AC power adapter

PORTS/SLOTS

Rear I/O Ports

Two (2) Type-A Hi-Speed USB 480Mbps signaling rate ports

Two (2) Type-A SuperSpeed USB 5Gbps signaling rate ports

One (1) RJ-45 (network) jack

One (1) HDMI 1.4 out connector

One (1) Microphone/Headphone Combo Jack

One (1) DC in power

Bottom I/O Ports

One (1) 3 in 1 Card reader (SD, SDHC, SDXC)

Internal I/O Ports

One (1) M.2 PCIe x1 2230 (for WLAN)

One (1) M.2 PCIe x4 2280 for Intel® Core™ / One (1) M.2 PCIe x1 2280 for Intel® Pentium® configurations

One (1) SATA storage connector

Bays

One (1) 3.5" internal storage drive



WEIGHTS & DIMENSIONS

Weight

21.5 Non-Touch Product Weight (Unboxed) Without Stand

5.15 kg, 11.35 lbs

Basic Stand

5.7 kg, 12.57 lbs

21.5 Shipping Weight (Boxed) 8.16 kg, 17.99 lbs

21.5 Shipping Weight (Pallet) 167.61 kg, 369.52 lbs

Dimension

21.5 System Dimensions Without Stand

490.3 x 322.0 x 58.1 mm 19.3 x 12.68 x 2.29 in

Basic Stand

490.3 x 380.74 x 204.51 mm 19.3 x 14.99 x 8.05 in

21.5 Shipping Dimensions (Boxed) 593 x 478 x 243 mm, 23.35 x 18.82 x 9.57 in

21.5 Shipping Dimensions (Pallet) 1186 x 972 x 1569 mm, 46.69 x 38.27 x 61.77 in

21.5 Pallet Quantity (including Touch, Non-Touch) 24



UNIT ENVIRONMENT AND OPERATING CONDITIONS9

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's recirculated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature RangeOperating: 50° to 95° F (10° to 35° C)*

Non-operating: -22° to 140° F(-30° to 60° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 5% to 95% (non-condensing at ambient)

Maximum Altitude (unpressurized) Operating: 5000m

Non-operating: 50000ft (15240 m)

NOTE:. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.





Technical Specifications – Display

ALL-IN-ONE DISPLAY PANEL SPECIFICATIONS

21.5" diagonal FHD IPS anti-glare WLED-backlit (1920 x 1080)

Non-touch

Type IPS WLED Backlit LCD
Active area (mm) 476.064 x 267.786
Native resolution (HxV) 1920 x 1080

Refresh rate 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.24795 x 0.24795

Contrast ratio (typical) 1000:1

Brightness (typical) 250nits

Viewing angle (typical) (HxV) 178° x 178°

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with the use of FRC technology

Color gamut (typical)

Anti-glare

Response time (typical)

NTSC 72%

Yes

14ms

Default color temperature Warm (6500K)

NOTE: All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

21.5" diagonal FHD VA anti-glare WLED-backlit (1920 x 1080)

Non-touch

 Type
 VA WLED Backlit LCD

 Active area (mm)
 476.064 x 267.786

 Native resolution (HxV)
 1920 x 1080

Refresh rate 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.24795 x 0.24795

Contrast ratio (typical)3000:1Brightness (typical)250nitsViewing angle (typical) (HxV)178° x 178°

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with the use of FRC technology

Color gamut (typical)NTSC 72%Anti-glareYesResponse time (typical)18ms

Default color temperature Warm (6500K)

NOTE: All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications – Stand

ALL-IN-ONE STAND SPECIFICATIONS

Articulating Stand

Tilt Angle
Rotation (Swivel)
None
None

490.3 mm

58.10 mm

58.74 mm





Technical Specifications – Storage

STORAGE AND DRIVES

500 GB 7200RPM 3.5in SATA HDD

Capacity500 GBRotational Speed7,200 rpmInterfaceSATA 6.0 Gb/s

Buffer Size 32 MB

 Logical Blocks
 976,773,168

 Seek Time
 11 ms (Average)

 Height
 1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 3.5in SATA HDD

Capacity 1 TB
Rotational Speed 7,200 rpm
Interface SATA 6 Gb/s
Buffer Size 64 MB

 Logical Blocks
 1,953,525,168

 Seek Time
 11 ms (Average)

 Height
 1 in/2.54 cm

Width (nominal) Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 7200RPM 3.5in SATA HDD

Capacity2 TBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size64 MB

 Logical Blocks
 3,907,029,168

 Seek Time
 11 ms (Average)

 Height
 1.028 in/26.11 mm

 Width (nominal)
 4.0 in/101.6 mm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.





Technical Specifications – Storage

256 GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10a Capacity 256 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 1600MB/s **Maximum Sequential Write** Up to 780MB/s **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10q Capacity 512 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 1600MB/s **Maximum Sequential Write** Up to 860MB/s 1.000,215,216 Logical Blocks

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q Capacity 128 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 2800MB/s **Maximum Sequential Write** Up to 600MB/s **Logical Blocks** 250,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.





Technical Specifications – Storage

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10a 256GB Capacity Height 2.38mm 80mm Length Width 22_{mm} Interface PCIE Gen3 **Maximum Sequential Read** Up to 2700MB/s **Maximum Sequential Write** Up to 1000MB/s **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10a Capacity 512 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 2900MB/s **Maximum Sequential Write** Up to 1100MB/s **Logical Blocks** 1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 9.5mm Slim DVD Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

 Weight (max)
 0.31 lb (140 g)

 Write Speeds
 DVD-R DL - Up to 6X

DVD+R - Up to 8X DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X

Read Speeds DVD-RW, DVD+RW - Up to 8X



Technical Specifications – Storage

DVD-R DL, DVD+R DL - Up to 8X DVD+R, DVD-R - Up to 8X

DVD-ROM DL, DVD-ROM - Up to 8X

CD-ROM, CD-R - Up to 24X

CD-RW - Up to 24X

Access time

(typical reads, including

settling) Power Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Stop Time 6 seconds (typical)

Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions (operating - non-condensing)

Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)





Technical Specifications - Audio

HIGH DEFINITION AUDIO

Type Integrated

HD Audio Codec Realtek ALC3247 Audio Codec

Audio I/O Ports Rear 3.5mm combo (microphone/headphone) jack (32 0hm) supporting CTIA and OMTP style

headset

Microphone(2K Ohm)

Analog Audio Yes

Internal Speaker Amplifier 2W per channel stereo amplifier for the internal speakers only

Internal Speaker Yes - Stereo Speaker

 DAC Sampling Rates
 44.1 kHz/48 kHz/96 kHz/192 kHz

 ADC Sampling Rates
 44.1 kHz/48 kHz/96 kHz/192 kHz





Technical Specifications – Input/Output

INPUT/OUTPUT DEVICES

HP Universal USB Wired Keyboard

Keys 104, 105 layout (depending upon country)

Physical Characteristics Dimensions 18.15 x 6.02 x 1.08 in (461 x 153 x 27.4 mm) (L x W x H)

Weight 1.32 lb (600g) min

Operating voltage 5 VDC, +/-5%

Power consumption 50mA Max (All LED on)

Electrical System interface USB Type A plug connector

ESD Contact Discharge: 8 KV Air Discharge: 15 KV

EMI - RFI Conforms to FCC rules for a Class B computing device

Keycaps Mid-profile design

Switch actuation 60±10g nominal peak force with tactile feedback

Switch life 10 million keystrokes (Life tester)

Mechanical

Switch type Contamination-resistant switch membrane

Key-leveling mechanisms For all double-wide and greater-length keys

Cable length 6 ft (1.8 m)

Acoustics 43-dBA maximum sound pressure level

Operating temperature 50° to 122° F (10° to 50° C) Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)
Non-operating humidity 20% to 80% (non-condensing at ambient)

Environmental Operating shock 40 g, six surfaces

Non-operating shock 80 g, six surfaces
Operating vibration 2-g peak acceleration

Non-operating vibration 4-g peak acceleration

Drop (out of box) 26 in (66 cm) on carpet, six-drop sequence

Drop (in box) 30 in (76.2 cm) on concrete, 16-drop sequence



Technical Specifications – Input/Output

HP USB Universal Wired Mouse

Dimensions (H x L x W) 4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)

Weight 0.19lb (90g)

Operating temperature 50° to 122° F (10° to 50° C)

Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)

Non-operating humidity 20% to 80% (non-condensing at ambient)

Environmental Operating shock 50 g, 6 surfaces

Non-operating shock 80 g, 6 surfaces

Operating vibration 2-g peak acceleration
Non-operating vibration 4-g peak acceleration

Operating voltage 5 VDC, +/-5%

Power consumption 50mA Max

Electrical Resolution 800, 1200, 1600 DPI

Tracking speed 31 inch/sec (max)

Tracking acceleration 8G(max), 1G=9.8m/s3

Connector USB 2.0

Cable length 6 ft (1.8 m)



Mechanical

Technical Specifications – Input/Output

HP USB Optical Mouse

Environmental

Electrical

Mechanical

Dimensions (H x L x W) 4.53 x 2.50 x 1.40 in (115 x 63.46 x 35.48 mmm)

Weight 0.18lb (80g)

Operating temperature 50° to 122° F (10° to 50° C)

Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)

Non-operating humidity 20% to 80% (non-condensing at ambient)

Operating shock 40 g, six surfaces

Non-operating shock 80 g, six surfaces

Operating vibration 2-g peak acceleration

Operating vibration 2-g peak acceleration
Non-operating vibration 4-g peak acceleration

Operating voltage 5 VDC, +/-5%

Power consumption 50mA Max

Resolution 1,000 DPI

Sensor Pixart PAN3606DL

Tracking speed 30 inch/sec (max)

Tracking acceleration 9G(max), 1G=9.8m/s2

Connector USB 2.0

Cable length 6 ft (1.8 m)



Technical Specifications - Networking

NETWORKING/COMMUNICATIONS

| Realtek® RTL8111HSH-CG Gigabit Ethernet Controller | Ethernet Features | 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) |
|---|------------------------|--|
| | | IEEE 802.3az EEE (Energy Efficient Ethernet) Jumbo Frame 9K Auto MDI/MDIX Crossover cable detection |
| | Power Management | ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption |
| | Performance Features | TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling |
| | Manageability | Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status |
| | Interface | PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ |
| | NIC Device Driver Name | PCIe GBE Ethernet Family Controller |

WLAN*

| Realtek RTL8822CE Wi-Fi | i 5¹ (802.11ac) 2x2 with Bluetooth® M.2 | | |
|---|--|--|--|
| Wireless LAN Standards | IEEE 802.11a | | |
| | IEEE 802.11b | | |
| | IEEE 802.11g | | |
| | IEEE 802.11n | | |
| | IEEE 802.11ac | | |
| | IEEE 802.11d | | |
| | IEEE 802.11e | | |
| | IEEE 802.11h | | |
| | IEEE 802.11i | | |
| | IEEE 802.11k | | |
| | IEEE 802.11r | | |
| | IEEE 802.11v | | |
| *NOTE: Wireless access point ar backwards compatible with prio | nd internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 is pr 802.11 specs. | | |
| Interoperability | Wi-Fi® certified | | |
| Frequency Band | 802.11b/g/n | | |
| | • 2.402 – 2.482 GHz | | |
| | 802.11a/n | | |
| | • 4.9 – 4.95 GHz (Japan) | | |
| | • 5.15 – 5.25 GHz | | |
| | • 5.25 – 5.35 GHz | | |



| | • 5.47 – 5.725 GHz | | |
|-----------------------------------|---|--|--|
| | • 5.825 – 5.850 GHz | | |
| Data Rates | • 802.11b: 1, 2, 5.5, 11 Mbps | | |
| | • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps | | |
| | • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps | | |
| | • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) | | |
| | • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz) | | |
| Modulation | Direct Sequence Spread Spectrum | | |
| Security ² | BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM • IEEE 64 / 128 bit WEP encryption for a/b/g mode only | | |
| Security | AES-CCMP: 128 bit in hardware | | |
| | • 802.1x authentication | | |
| | WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. | | |
| | WPA2 certification | | |
| | • IEEE 802.11i | | |
| | • WAPI | | |
| Network Architecture | Ad-hoc (Peer to Peer) | | |
| Models | Infrastructure (Access Point Required) | | |
| Roaming | IEEE 802.11 compliant roaming between access points | | |
| Output Power ³ | • 802.11b : +18.5dBm minimum | | |
| | • 802.11g : +17.5dBm minimum | | |
| | • 802.11a : +18.5dBm minimum | | |
| | • 802.11n HT20(2.4GHz): +15.5dBm minimum | | |
| | • 802.11n HT40(2.4GHz): +14.5dBm minimum | | |
| | • 802.11n HT20(5GHz): +15.5dBm minimum | | |
| | • 802.11n HT40(5GHz): +14.5dBm minimum | | |
| | • 802.11ac VHT80(5GHz): +11.5dBm minimum | | |
| Power Consumption | • 802.11ac VHT160(5GHz): +11.5dBm minimum • Transmit mode: 2.0 W | | |
| Power Consumption | • Fransmit mode :2.0 w | | |
| | • Idle mode (PSP) 180 mW (WLAN Associated) | | |
| | • Idle mode :50 mW (WLAN unassociated) | | |
| | Connected Standby/Modern Standby: 10mW | | |
| | • Radio disabled: 8 mW | | |
| Power Management | ACPI and PCI Express compliant power management | | |
| - | 802.11 compliant power saving mode | | |
| Receiver Sensitivity ⁴ | 802.11b, 1Mbps : -93.5dBm maximum | | |
| | 802.11b, 11Mbps : -84dBm maximum | | |
| | 802.11a/g, 6Mbps : -86dBm maximum | | |
| | 802.11a/g, 54Mbps:-72dBm maximum | | |
| | 802.11n, MCS07 : -67dBm maximum | | |
| | 802.11n, MCS15 : -64dBm maximum | | |
| | 802.11ac, MCS0 : -84dBm maximum | | |
| Automorton | 802.11ac, MCS9: -59dBm maximum | | |
| Antenna type | High efficiency antenna with spatial diversity, mounted in the display enclosure Two | | |
| | embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications | | |
| Form Factor | PCI-Express M.2 MiniCard | | |
| Dimensions | Type 2230: 2.3 x 22.0 x 30.0 mm | | |
| Weight | Type 2230: 2.8q | | |
| Operating Voltage | 3.3v +/- 9% | | |
| Temperature | Operating 14° to 158° F (–10° to 70° C) | | |
| . Ciliperature | Non-operating | | |
| Humidity | Operating 10% to 90% (non-condensing) | | |
| | Non-operating 5% to 95% (non-condensing) | | |
| Altitude | Operating 0 to 10,000 ft (3,048 m) | | |
| | Non-operating 0 to 50,000 ft (15,240 m) | | |
| | | | |





| LED Activity | LED Amber – Radio OFF; LED White – Radio ON | | |
|---|---|--|--|
| 1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. 2. Must be | | | |

- configured at time of purchase.
- 2. Check latest software/driver release for updates on supported security features.
- 3. Maximum output power may vary by country according to local regulations.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

| (OFDM modulation). | | | |
|--|--|--|--|
| HP Integrated Module with Blue | etooth 4.0/4.1/4.2/5.0 Wireless Technology | | |
| Bluetooth® Specification | 4.0/4.1/4.2/5.0 Compliant | | |
| Frequency Band | 2402 to 2480 MHz | | |
| Number of Available Channels | Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH) | | |
| Data Rates and Throughput | Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps | | |
| Duta Rates and Throughput | BLE: 1 Mbps data rate; throughput up to 0.2 Mbps | | |
| | Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) | | |
| Transmit Power | The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR. | | |
| Power Consumption | Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW | | |
| Bluetooth® Software Supported Link Topology | Microsoft Windows Bluetooth® Software | | |
| Power Management | Microsoft Windows ACPI, and USB Bus Support | | |
| Certifications | FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark | | |
| Bluetooth Profiles Supported | BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) | | |



| | (802.11ac) 1x1 with Bluetooth® M.2 | | |
|-----------------------------------|--|--|--|
| Wireless LAN Standards | IEEE 802.11a | | |
| | IEEE 802.11b | | |
| | IEEE 802.11g | | |
| | IEEE 802.11n | | |
| | IEEE 802.11ac | | |
| Interoperability | Wi-Fi® certified | | |
| Frequency Band | 802.11b/g/n | | |
| | • 2.402 – 2.482 GHz | | |
| | 802.11a/n | | |
| | • 4.9 – 4.95 GHz (Japan) | | |
| | • 5.15 – 5.25 GHz | | |
| | • 5.25 – 5.35 GHz | | |
| | • 5.47 – 5.725 GHz | | |
| | • 5.825 – 5.850 GHz | | |
| Data Rates | • 802.11b: 1, 2, 5.5, 11 Mbps | | |
| | • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps | | |
| | • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps | | |
| | • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) | | |
| | • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz) | | |
| Modulation | Direct Sequence Spread Spectrum | | |
| | BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM | | |
| Security ² | • IEEE 64 / 128 bit WEP encryption for a/b/g mode only | | |
| | AES-CCMP: 128 bit in hardware | | |
| | • 802.1x authentication | | |
| | • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. | | |
| | WPA2 certification | | |
| | • IEEE 802.11i | | |
| | Cisco Certified Extensions, all versions through CCX4 and CCX Lite | | |
| | • WAPI | | |
| Network Architecture | Ad-hoc (Peer to Peer) | | |
| Models | Infrastructure (Access Point Required) | | |
| Roaming | IEEE 802.11 compliant roaming between access points | | |
| Output Power ³ | • 802.11b : +14dBm minimum | | |
| | • 802.11g : +12dBm minimum | | |
| | • 802.11a: +12dBm minimum | | |
| | • 802.11n HT20(2.4GHz): +12dBm minimum | | |
| | • 802.11n HT40(2.4GHz): +12dBm minimum | | |
| | • 802.11n HT20(5GHz): +10dBm minimum | | |
| | • 802.11n HT40(5GHz): +10dBm minimum | | |
| D | • 802.11ac VHT80(5GHz): +10dBm minimum | | |
| Power Consumption | • Transmit mode2.0 W | | |
| | • Receive mode 1.6 W | | |
| | • Idle mode (PSP) 180 mW (WLAN Associated) | | |
| | • Idle mode 50 mW (WLAN unassociated) | | |
| | Connected Standby 10mW Padio disabled 8 mW | | |
| Device Management | Radio disabled 8 mW ACRI and BCI Express compliant power management | | |
| Power Management | ACPI and PCI Express compliant power management | | |
| Dogging Compitition 4 | 802.11 compliant power saving mode | | |
| Receiver Sensitivity ⁴ | 802.11b, 1Mbps: -93.5dBm maximum | | |
| | 802.11b, 11Mbps : -84dBm maximum | | |
| | 802.11a/g, 6Mbps : -86dBm maximum | | |
| | 802.11a/g, 54Mbps: -72dBm maximum | | |
| | 802.11n, MCS07 : -67dBm maximum | | |
| | 802.11n, MCS15 : -64dBm maximum | | |
| | 802.11ac, MCS0 : -84dBm maximum | | |
| | 802.11ac, MCS9 : -59dBm maximum | | |





| Antenna type | One embedded dua | High efficiency antenna. One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN | | |
|-------------------|----------------------------|--|--|--|
| Form Factor | | communications and Bluetooth communications PCI-Express M.2 MiniCard | | |
| Dimensions | • | Type 2230 : 2.3 x 22.0 x 30.0 mm | | |
| Weight | Type 2230 : 2.8g | | | |
| Operating Voltage | 3.3v +/- 9% | 3.3v +/- 9% | | |
| Temperature | Operating Non-operating | 14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C) | | |
| Humidity | Operating Non-operating | 10% to 90% (non-condensing) 5% to 95% (non-condensing) | | |
| Altitude | Operating Non-operating | 0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m) | | |
| LED Activity | LED Amber – Radio | LED Amber – Radio OFF; LED White – Radio ON | | |

- 1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. 2. Must be configured at time of purchase.
- 2. Check latest software/driver release for updates on supported security features.
- 3. Maximum output power may vary by country according to local regulations.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

| Bluetooth® Specification | etooth® 4.0/4.1/4.2 Wireless Technology | |
|--|---|--|
| <u> </u> | 4.0/4.1/4.2 Compliant | |
| Frequency Band | 2402 to 2480 MHz | |
| Number of Available Channels | Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH) | |
| Data Rates and Throughput | Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps | |
| | BLE : 1 Mbps data rate; throughput up to 0.2 Mbps | |
| | Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) | |
| Transmit Power | The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR. | |
| Power Consumption | Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW | |
| Bluetooth® Software Supported Link Topology | Microsoft Windows Bluetooth® Software | |
| Power Management | Microsoft Windows ACPI, and USB Bus Support | |
| Certifications | ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark | |
| Bluetooth Profiles Supported | BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) | |



| Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) |
|---|
| Advanced Addio Distribution Fronte (AZDF) |



Technical Specifications - Power

POWER

Efficiency 65W EPS, 88% average efficiency at 115V & 89% at 230Vac

Operating Voltage Range 90Vac~264Vac **Rated Voltage Range** 100Vac~240Vac **Rated Line Frequency** 50Hz~60Hz **Operating Line Frequency** 47Hz~63Hz **Rated Input Current** ≤1.6A

Rated Input Current with Energy

Efficient* Power Supply

+19.5V

≤1.6A

DC Output

Current Leakage (NFPA 99: 2102) Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as

required for Non-Patient Electrical Appliances and Equipment used in a patient care facility or

that contact patients in normal use. Per section 10.3.5.1.

Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-Patient Electrical Appliances and Equipment used in a patient care

facility or that contact patients in normal use. Per section 10.3.5.1.

Dimensions 102 x 55 x 30 mm

Technical Specifications - Additional Features

ADDITIONAL FEATURES

Description

SMART Technology (Self-Monitoring, Analysis and Reporting Technology)

Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted





Technical Specifications - Environmental

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

IT ECO declaration

System Configuration

Energy Consumption (in accordance with US ENERGY STAR® test method)

Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".

115VAC, 60Hz

230VAC. 50Hz

100VAC, 50Hz

NOTE: Energy efficiency data listed is for an ENERGY STAR® certified product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® certified configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/qo/options

Heat Dissipation*

Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off 115VAC, 60Hz

230VAC, 50Hz

100VAC, 50Hz

NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

Typically Configured – Idle Fixed Disk – Random writes **Longevity and Upgrading**

Sound Power (Lwad, bels)

Sound Pressure (L_{pAm}, decibels)

Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

This product can be upgraded, possibly extending its useful life by several years.

Batteries This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight

Battery size: CR2032 (coin cell)

Battery type: Lithium





Technical Specifications - Environmental

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 38.3% post-consumer recycled plastic (by wt.)
- This product is 95.8% recycle-able when properly disposed of at end of life.

Packaging Materials

Material Usage

External: PAPER/Corrugated

Internal: PLASTIC/EPE (Expanded Polyethylene)
PLASTIC/Polyethylene low density

The plastic packaging material contains at least 90% recycled content.

The corrugated paper packaging materials contains at least 80% recycled content. This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

- Ashestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- · Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.



Technical Specifications - Environmental

- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to:

http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and resell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certifications:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Summary of Changes

SUMMARY OF CHANGES

| Date of change: | Version History: | | Description of change: |
|--------------------|------------------|----------|--|
| March 13, 2020 | V1 to V2 | Update | First page call out number 1 corrected. |
| June 16, 2020 | V2 to V3 | Update | Rear image call outs and rear I/O ports updated |
| July 20, 2020 | V3 to V4 | Update | Rear image call out #9 and ports section speed corrected |
| September 24, 2020 | V4 to V5 | Addition | Xerox® DocuShare® and footnote to software section. |
| December 3, 2020 | V5 to V6 | Removal | Energy Star and EPEAT on Page 3, Page 28 |

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